

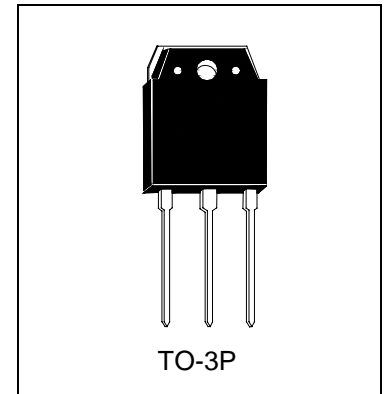


# HSC2625

NPN EPITAXIAL PLANAR TRANSISTOR

## Description

The HSC2625 is designed for triple diffused planer type high voltage, high speed switching applications.



## Absolute Maximum Ratings (Ta=25°C)

- Maximum Temperatures  
 Storage Temperature ..... -55 ~ +150 °C  
 Junction Temperature..... +150 °C Maximum
- Maximum Power Dissipation  
 Total Power Dissipation (Tc=25°C) ..... 80 W
- Maximum Voltages and Currents  
 VCBO Collector to Base Voltage ..... 450 V  
 VCEO Collector to Emitter Voltage..... 400 V  
 VEBO Emitter to Base Voltage..... 7 V  
 IC Collector Current ..... 10 A  
 IB Base Current..... 3 A

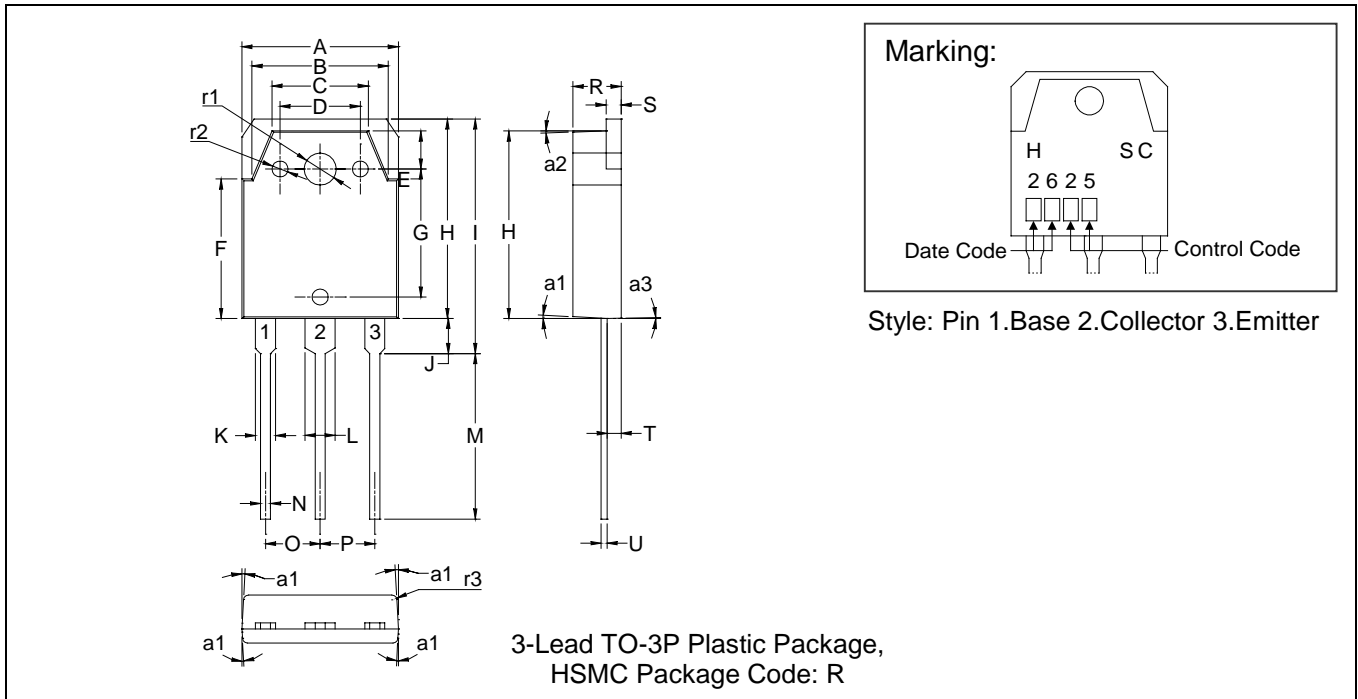
## Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	450	-	-	V	IC=1mA
BVCEO	400	-	-	V	IC=10mA
BVEBO	7	-	-		IE=100uA
ICBO	-	-	1	mA	VCB=450V
IEBO	-	-	100	uA	VEB=7V
*VCE(sat)	-	-	1.2	V	IC=4A, IB=800mA
*VBE(sat)	-	-	1.5	V	IC=4A, IB=800mA
*hFE1	10	-	30		IC=0.5A, VCE=5V
*hFE2	6	-	-		IC=4A, VCE=5V

\*Pulse Test: Pulse Width ≤380us, Duty Cycle≤2%



### TO-3P Dimension



DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.6063	0.6220	15.40	15.80	N	0.0315	0.0472	0.80	1.20
B	0.5276	0.5433	13.40	13.80	O	0.2028	0.2264	5.15	5.75
C	0.3701	0.3858	9.40	9.80	P	0.2028	0.2264	5.15	5.75
D	-	*0.3150	-	*8.00	Q	0.7283	0.7441	18.50	18.90
E	0.1417	0.1575	3.60	4.00	R	0.1811	0.1969	4.60	5.00
F	0.5394	0.5551	13.70	14.10	S	0.0571	0.0650	1.45	1.65
G	0.4945	0.5102	12.56	12.96	T	0.0472	0.0630	1.20	1.60
H	0.7756	0.7913	19.70	20.10	a1	-	*3°	-	*3°
I	0.9134	0.9291	23.20	23.60	a2	-	*2°	-	*2°
J	0.1299	0.1457	3.30	3.70	a3	-	*1°	-	*1°
K	0.0709	0.0866	1.80	2.20	r1	φ3.10	φ3.30	φ3.10	φ3.30
L	0.1102	0.1260	2.80	3.20	r2	-	*φ1.60	-	*φ1.60
M	0.6378	0.6614	16.20	16.80	r3	-	*R0.50	-	*R0.50

- Notes: 1.Dimension and tolerance based on our Spec. dated Apr. 25,1996.  
 2.Controlling dimension: millimeters.  
 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.  
 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

**Material:**

- Lead: 42 Alloy; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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